

Reg No.: _____

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APJ ABDUL KALAM TECHNOLOGICAL UNIVERSITY
THIRD SEMESTER B.TECH DEGREE EXAMINATION(S), MAY 2019

Course Code: EC203

Course Name: SOLID STATE DEVICES (EC,AE)

Max. Marks: 100

Duration: 3 Hours

PART A

Answer any two full questions, each carries 15 marks.

Marks

- 1 a) Explain Fermi Dirac distribution function. Plot the Fermi Dirac distribution function for an intrinsic semiconductor. (4)
- b) Explain diffusion. Derive an expression for diffusion current density for an n-type semiconductor. (7)
- c) A Si sample is doped with 10^{17} As atoms/cm³. What is the equilibrium hole concentration p_0 at 300K? Where is E_F relative to E_i ? (4)
- 2 a) Draw the graph showing the distribution of excess carriers with respect to time in an n-type semiconductor. (3)
- b) Derive the expressions for equilibrium concentration of electrons and holes using Fermi Dirac distribution function. (6)
- c) A direct bandgap semiconductor has $n_i = 10^{10}$ cm⁻³ donors. Its low level carrier lifetime τ is $\tau_n = \tau_p = 10^{-7}$ s. (6)
 - i) If a sample of this material is uniformly exposed to a steady optical generation rate of $g_{op} = 2 \times 10^{22}$ EHP/cm²-s; Calculate the excess carrier concentration $\Delta_n = \Delta_p$
 Note : The excitation rate is not low level but assume that α_r is the same.
 - ii) If the carrier lifetime (τ) is defined as the excess carrier concentration divided by the recombination rate, what is τ at this excitation level?
- 3 a) Explain High field effects. (4)
- b) Derive and explain Einstein relations. (6)
- c) A Ge sample is doped with 10^{17} Boron atoms/cm³. Determine the carrier concentration & Fermi level position at room temperature. n_i for Ge = 2.5×10^{13} cm⁻³ at room temperature. (5)

PART B*Answer any two full questions, each carries 15 marks.*

- 4 a) Draw and explain the VI characteristics of PN junction diode. (4)
- b) Explain the different types of capacitances associated with a p-n junction. (6)
- c) The following data are given for a Si abrupt pn junction at 300K, $A=1\text{cm}^2$, $V_o=0.6\text{V}$. (5)

P- side	N-side
$N_A = 10^{18} \text{ cm}^{-3}$	$N_D = 10^{16} \text{ cm}^{-3}$
$\tau_n = 50 \mu\text{s}$	$\tau_p = 10 \mu\text{s}$
$D_n = 34 \text{ cm}^2 / \text{s}$	$D_p = 13 \text{ cm}^2 / \text{s}$

Calculate $I_p(x_n = 0)$; $I_n(x_p = 0)$ & the total diode current ; (Given $kT/q = 0.026 \text{ V}$)

- 5 a) Derive the ideal diode equation. (10)
- b) Differentiate between Zener and Avalanche breakdown mechanisms. (5)
- 6 a) Derive an expression for the contact potential of an open circuit p-n junction. (7)
- b) Write short notes on metal semiconductor contacts. (8)

PART C*Answer any two full questions, each carries 20 marks.*

- 7 a) Explain the principle of operation of MOS capacitor with suitable energy band diagrams. (10)
- b) Explain base width modulation with neat diagrams. (4)
- c) Briefly explain (6)
- i) MOSFET scaling.
- ii) Hot electron effect.
- 8 a) Derive the expression for minority carrier distribution and terminal currents of a pnp transistor. (14)
- b) Explain the capacitance – voltage relation for a MOS capacitor with neat diagram. (6)
- 9 a) Explain the principle of operation of FINFET. (7)
- b) With neat diagrams, explain the flow of different current components in a pnp transistor under active mode of operation. (7)
- c) Draw and explain the drain characteristics of an n-channel MOSFET. (6)
